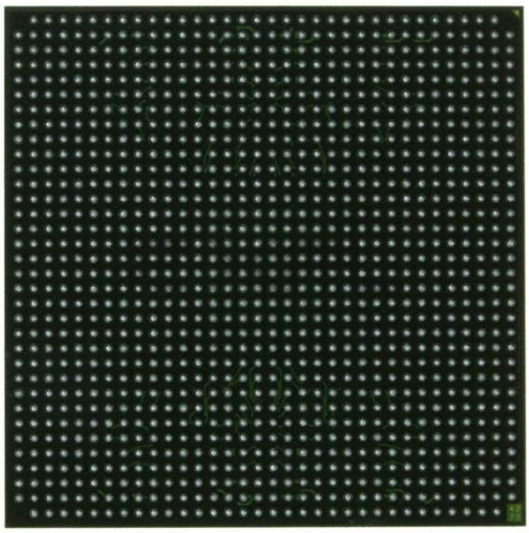

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2320
Number of Logic Elements/Cells	20880
Total RAM Bits	1622016
Number of I/O	564
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp20-5ff1152i

Functional Description: FPGA

Input/Output Blocks (IOBs)

Virtex-II Pro I/O blocks (IOBs) are provided in groups of two or four on the perimeter of each device. Each IOB can be used as input and/or output for single-ended I/Os. Two IOBs can be used as a differential pair. A differential pair is always connected to the same switch matrix, as shown in Figure 18.

IOB blocks are designed for high-performance I/O, supporting 22 single-ended standards, as well as differential signaling with LVDS, LDT, bus LVDS, and LVPECL.

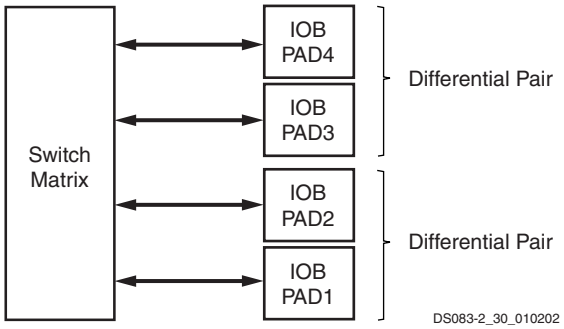

Figure 18: **Virtex-II Pro Input/Output Tile**

Note: Differential I/Os must use the same clock.

Supported I/O Standards

Virtex-II Pro IOB blocks feature SelectIO-Ultra inputs and outputs that support a wide variety of I/O signaling standards. In addition to the internal supply voltage (V_{CCINT} = 1.5V), output driver supply voltage (V_{CCO}) is dependent on the I/O standard (see Table 8 and Table 9). An auxiliary supply voltage (V_{CCAUX} = 2.5V) is required, regardless of the I/O standard used. For exact supply voltage absolute maximum ratings, see Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics.

All of the user IOBs have fixed-clamp diodes to V_{CCO} and to ground. The IOBs are not compatible or compliant with 5V I/O standards (not 5V-tolerant).

Table 10 lists supported I/O standards with Digitally Controlled Impedance. See Digitally Controlled Impedance (DCI), page 31.

Table 8: **Supported Single-Ended I/O Standards**

IOSTANDARD Attribute	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Board Termination Voltage (V_{TT})
LVTTL(1)	3.3	3.3	N/R	N/R
LVCMOS33(1)	3.3	3.3	N/R	N/R
LVCMOS25	2.5	2.5	N/R	N/R
LVCMOS18	1.8	1.8	N/R	N/R
LVCMOS15	1.5	1.5	N/R	N/R
PCI33_3	Note (2)	Note (2)	N/R	N/R
PCI66_3	Note (2)	Note (2)	N/R	N/R
PCIX	Note (2)	Note (2)	N/R	N/R
GTL	Note (3)	Note (3)	0.8	1.2
GTLP	Note (3)	Note (3)	1.0	1.5
HSTL_I	1.5	N/R	0.75	0.75
HSTL_II	1.5	N/R	0.75	0.75
HSTL_III	1.5	N/R	0.9	1.5
HSTL_IV	1.5	N/R	0.9	1.5
HSTL_I_18	1.8	N/R	0.9	0.9
HSTL_II_18	1.8	N/R	0.9	0.9
HSTL_III _18	1.8	N/R	1.1	1.8
HSTL_IV_18	1.8	N/R	1.1	1.8
SSTL2_I	2.5	N/R	1.25	1.25
SSTL2_II	2.5	N/R	1.25	1.25
SSTL18_I (4)	1.8	N/R	0.9	0.9
SSTL18_II	1.8	N/R	0.9	0.9

Notes:
1. Refer to **XAPP659** for more details on interfacing to these 3.3V standards.
2. For PCI and PCI-X standards, refer to **XAPP653**.
3. V_{CCO} of GTL or GTLP should not be lower than the termination voltage or the voltage seen at the I/O pad. *Example:* If the pin High level is 1.5V, connect V_{CCO} to 1.5V.
4. SSTL18_I is not a JEDEC-supported standard.
5. N/R = no requirement.

Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics

DS083 (v5.0) June 21, 2011 **Product Specification**

Virtex-II Pro[1] Electrical Characteristics

Virtex™-II Pro devices are provided in -7, -6, and -5 speed grades, with -7 having the highest performance.

Virtex-II Pro DC and AC characteristics are specified for both commercial and industrial grades. Except the operating temperature range or unless otherwise noted, all the DC and AC electrical parameters are the same for a particular speed grade (that is, the timing characteristics of a -6 speed grade industrial device are the same as for a -6 speed grade commercial device). However, only selected speed grades and/or devices might be available in the industrial range.

All supply voltage and junction temperature specifications are representative of worst-case conditions. The parameters included are common to popular designs and typical applications. Contact Xilinx for design considerations requiring more detailed information.

All specifications are subject to change without notice.

Virtex-II Pro DC Characteristics

Table 1: **Absolute Maximum Ratings**

Symbol	Description[1]		Virtex-II Pro X	Virtex-II Pro	Units
V_{CCINT}	Internal supply voltage relative to GND		–0.5 to 1.6		V
V_{CCAUX}	Auxiliary supply voltage relative to GND		–0.5 to 3.0		V
V_{CCO}	Output drivers supply voltage relative to GND		–0.5 to 3.75		V
V_{BATT}	Key memory battery backup supply		–0.5 to 4.05		V
V_{REF}	Input reference voltage		–0.3 to 3.75		V
V_{IN}	3.3V I/O input voltage relative to GND (user and dedicated I/Os)		–0.3 to 4.05[3]		V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)		–0.5 to V_{CCO} + 0.5		V
V_{TS}	Voltage applied to 3-state 3.3V output (user and dedicated I/Os)		–0.3 to 4.05[3]		V
	Voltage applied to 3-state 2.5V or below output (user and dedicated I/Os)		–0.5 to V_{CCO} + 0.5		V
AVCCAUXRX	Receive auxilliary supply voltage relative to GNDA (analog ground)		–0.5 to 2.0	–0.5 to 3.0	V
AVCCAUXTX	Transmit auxilliary supply voltage relative to GNDA (analog ground)		–0.5 to 3.0	–0.5 to 3.0	V
V_{TRX}	Terminal receive supply voltage relative to GND		–0.5 to 3.0	–0.5 to 3.0	V
V_{TTX}	Terminal transmit supply voltage relative to GND		–0.5 to 1.6	–0.5 to 3.0	V
T_{STG}	Storage temperature (ambient)		–65 to +150		°C
T_{SOL}	Maximum soldering temperature[2]	All regular FG/FF flip-chip packages	+220		°C
		Pb-free FGG256 wire-bond package	N/A	+260	°C
		Pb-free FGG456 and FGG676 wire-bond packages	N/A	+250	°C
T_J	Maximum junction temperature[2]		+125		°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
2. For soldering guidelines and thermal considerations, see the **Device Packaging and Thermal Characteristics Guide** information on the Xilinx website.
3. 3.3V I/O Absolute Maximum limit applied to DC and AC signals. Refer to **XAPP659** for more details.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device initialization. The actual current consumed depends on the power-on ramp rate of the power supply.

The V_{CCINT} power supply must ramp on, monotonically, no faster than 200 µs and no slower than 50 ms. Ramp-on is defined as: 0 V_{DC} to minimum supply voltages (see Table 2).

V_{CCAUX} and V_{CCO} can power on at any ramp rate. Power supplies can be turned on in any sequence.

Table 5 shows the minimum current required by Virtex-II Pro devices for proper power-on and configuration.

If the current minimums shown in Table 5 are met, the device powers on properly after all three supplies have passed through their power-on reset threshold voltages.

Once initialized and configured, use the power calculator to estimate current drain on these supplies.

For more information on V_{CCAUX}, V_{CCO}, and configuration mode, refer to Chapter 3 in the *Virtex-II Pro Platform FPGA User Guide*.

Table 5: **Power-On Current for Virtex-II Pro Devices**

Symbol	Device											Units
	XC2VP2	XC2VP4	XC2VP7	XC2VP20	XC2VPX20	XC2VP30	XC2VP40	XC2VP50	XC2VP70	XC2VPX70	XC2VP100	
$I_{CCINTMIN}$	500	500	500	600	600	800	1050	1250	1700	1700	2200	mA
$I_{CCAUXMIN}$	250	250	250	250	250	250	250	250	250	250	250	mA
I_{CCOMIN}	100	100	100	100	100	100	100	100	100	100	100	mA

Notes:
1. Power-on current parameter values are specified for Commercial Grade. For Industrial Grade values, multiply Commercial Grade values by 1.5.
2. I_{CCOMIN} values listed here apply to the entire device (all banks).

General Power Supply Requirements

Proper decoupling of all FPGA power supplies is essential. Consult Xilinx Application Note **XAPP623** for detailed information on power distribution system design.

V_{CCAUX} powers critical resources in the FPGA. Therefore, this supply voltage is especially susceptible to power supply noise. V_{CCAUX} can share a power plane with V_{CCO}, but only if V_{CCO} does not have excessive noise. Staying within simultaneously switching output (SSO) limits is essential for keeping power supply noise to a minimum. Refer to **XAPP689**, "Managing Ground Bounce in Large FPGAs," to determine the number of simultaneously switching outputs allowed per bank at the package level.

Changes in V_{CCAUX} voltage beyond 200 mV peak-to-peak should take place at a rate no faster than 10 mV per millisecond.

Recommended practices that can help reduce jitter and period distortion are described in Xilinx Answer Record 13756.

CLB Distributed RAM Switching Characteristics

Table 43: **CLB Distributed RAM Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-7	-6	-5	
Sequential Delays					
Clock CLK to X/Y outputs (WE active) in 16 x 1 mode	$T_{SHCKO16}$	1.25	1.38	1.54	ns, max
Clock CLK to X/Y outputs (WE active) in 32 x 1 mode	$T_{SHCKO32}$	1.57	1.75	1.95	ns, max
Clock CLK to F5 output	$T_{SHCKOF5}$	1.52	1.68	1.88	ns, max
Setup and Hold Times Before/After Clock CLK					
BX/BY data inputs (DIN)	T_{DS}/T_{DH}	0.38/–0.07	0.41/–0.07	0.46/–0.08	ns, min
F/G address inputs	T_{AS}/T_{AH}	0.42/ 0.00	0.47/ 0.00	0.52/ 0.00	ns, min
SR input	T_{WES}/T_{WEH}	0.22/ 0.04	0.24/ 0.05	0.26/ 0.05	ns, min
Clock CLK					
Minimum Pulse Width, High	T_{WPH}	0.63	0.72	0.79	ns, min
Minimum Pulse Width, Low	T_{WPL}	0.63	0.72	0.79	ns, min
Minimum clock period to meet address write cycle time	T_{WC}	1.25	1.44	1.58	ns, min

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values cannot be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

CLB Shift Register Switching Characteristics

Table 44: **CLB Shift Register Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-7	-6	-5	
Sequential Delays					
Clock CLK to X/Y outputs	T_{REG}	2.78	3.12	3.49	ns, max
Clock CLK to X/Y outputs	T_{REG32}	3.10	3.49	3.90	ns, max
Clock CLK to XB output via MC15 LUT output	T_{REGXB}	2.84	3.18	3.55	ns, max
Clock CLK to YB output via MC15 LUT output	T_{REGYB}	2.55	2.88	3.21	ns, max
Clock CLK to Shiftout	T_{CKSH}	2.50	2.83	3.15	ns, max
Clock CLK to F5 output	T_{REGF5}	3.05	3.42	3.83	ns, max
Setup and Hold Times Before/After Clock CLK					
BX/BY data inputs (DIN)	T_{SRLDS}/T_{SRLDH}	0.70/–0.16	0.77/–0.18	0.98/–0.21	ns, min
SR input	T_{WSS}/T_{WSH}	0.27/ 0.01	0.34/ 0.01	0.47/ 0.01	ns, min
Clock CLK					
Minimum Pulse Width, High	T_{SRPH}	0.63	0.72	0.79	ns, min
Minimum Pulse Width, Low	T_{SRPL}	0.63	0.72	0.79	ns, min

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values cannot be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

Table 46: **Pipelined Multiplier Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-7	-6	-5	
Setup and Hold Times Before/After Clock					
Data Inputs	$T_{MULIDCK}/T_{MULCKID}$	1.86/ 0.00	2.06/ 0.00	2.31/ 0.00	ns, max
Clock Enable	$T_{MULIDCK\_CE}/T_{MULCKID\_CE}$	0.23/ 0.00	0.25/ 0.00	0.28/ 0.00	ns, max
Reset	$T_{MULIDCK\_RST}/T_{MULCKID\_RST}$	0.21/–0.09	0.24/–0.09	0.26/–0.10	ns, max
Clock to Output Pin					
Clock to Pin35	T_{MULTCK_P35}	2.45	2.92	3.27	ns, max
Clock to Pin34	T_{MULTCK_P34}	2.36	2.82	3.16	ns, max
Clock to Pin33	T_{MULTCK_P33}	2.28	2.72	3.05	ns, max
Clock to Pin32	T_{MULTCK_P32}	2.20	2.62	2.93	ns, max
Clock to Pin31	T_{MULTCK_P31}	2.12	2.52	2.82	ns, max
Clock to Pin30	T_{MULTCK_P30}	2.03	2.42	2.71	ns, max
Clock to Pin29	T_{MULTCK_P29}	1.95	2.32	2.60	ns, max
Clock to Pin28	T_{MULTCK_P28}	1.87	2.22	2.48	ns, max
Clock to Pin27	T_{MULTCK_P27}	1.79	2.12	2.37	ns, max
Clock to Pin26	T_{MULTCK_P26}	1.70	2.02	2.26	ns, max
Clock to Pin25	T_{MULTCK_P25}	1.62	1.92	2.15	ns, max
Clock to Pin24	T_{MULTCK_P24}	1.54	1.82	2.03	ns, max
Clock to Pin23	T_{MULTCK_P23}	1.46	1.71	1.92	ns, max
Clock to Pin22	T_{MULTCK_P22}	1.37	1.61	1.81	ns, max
Clock to Pin21	T_{MULTCK_P21}	1.29	1.51	1.69	ns, max
Clock to Pin20	T_{MULTCK_P20}	1.21	1.41	1.58	ns, max
Clock to Pin19	T_{MULTCK_P19}	1.13	1.31	1.47	ns, max
Clock to Pin18	T_{MULTCK_P18}	1.04	1.21	1.36	ns, max
Clock to Pin17	T_{MULTCK_P17}	0.96	1.11	1.24	ns, max
Clock to Pin16	T_{MULTCK_P16}	0.88	1.01	1.13	ns, max
Clock to Pin15	T_{MULTCK_P15}	0.80	0.91	1.02	ns, max
Clock to Pin14	T_{MULTCK_P14}	0.71	0.81	0.91	ns, max
Clock to Pin13	T_{MULTCK_P13}	0.63	0.71	0.79	ns, max
Clock to Pin12	T_{MULTCK_P12}	0.63	0.71	0.79	ns, max
Clock to Pin11	T_{MULTCK_P11}	0.63	0.71	0.79	ns, max
Clock to Pin10	T_{MULTCK_P10}	0.63	0.71	0.79	ns, max
Clock to Pin9	T_{MULTCK_P9}	0.63	0.71	0.79	ns, max
Clock to Pin8	T_{MULTCK_P8}	0.63	0.71	0.79	ns, max
Clock to Pin7	T_{MULTCK_P7}	0.63	0.71	0.79	ns, max
Clock to Pin6	T_{MULTCK_P6}	0.63	0.71	0.79	ns, max
Clock to Pin5	T_{MULTCK_P5}	0.63	0.71	0.79	ns, max
Clock to Pin4	T_{MULTCK_P4}	0.63	0.71	0.79	ns, max
Clock to Pin3	T_{MULTCK_P3}	0.63	0.71	0.79	ns, max
Clock to Pin2	T_{MULTCK_P2}	0.63	0.71	0.79	ns, max
Clock to Pin1	T_{MULTCK_P1}	0.63	0.71	0.79	ns, max
Clock to Pin0	T_{MULTCK_P0}	0.63	0.71	0.79	ns, max

Input Clock Tolerances

Table 58: **Input Clock Tolerances**

Description	Symbol	Constraints F_{CLKIN}	Speed Grade						Units
			–7		–6		–5		
			Min	Max	Min	Max	Min	Max	
Input Clock Low/High Pulse Width									
PSCLK	PSCLK_PULSE	< 1MHz	25.00		25.00		25.00		ns
PSCLK and CLKIN(3)	PSCLK_PULSE and CLKIN_PULSE	1 – 10 MHz	25.00		25.00		25.00		ns
		10 – 25 MHz	10.00		10.00		10.00		ns
		25 – 50 MHz	5.00		5.00		5.00		ns
		50 – 100 MHz	3.00		3.00		3.00		ns
		100 – 150 MHz	2.40		2.40		2.40		ns
		150 – 200 MHz	2.00		2.00		2.00		ns
		200 – 250 MHz	1.80		1.80		1.80		ns
		250 – 300 MHz	1.50		1.50		1.50		ns
		300 – 350 MHz	1.30		1.30		1.30		ns
		350 – 400 MHz	1.15		1.15		1.15		ns
		> 400 MHz	1.05		1.05		1.05		ns
Input Clock Cycle-Cycle Jitter (Low Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_CYC_JITT_DLL_LF			±300		±300		±300	ps
CLKIN (using CLKFX outputs)(2)	CLKIN_CYC_JITT_FX_LF			±300		±300		±300	ps
Input Clock Cycle-Cycle Jitter (High Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_CYC_JITT_DLL_HF			±150		±150		±150	ps
CLKIN (using CLKFX outputs)(2)	CLKIN_CYC_JITT_FX_HF			±150		±150		±150	ps
Input Clock Period Jitter (Low Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_PER_JITT_DLL_LF			±1		±1		±1	ns
CLKIN (using CLKFX outputs)(2)	CLKIN_PER_JITT_FX_LF			±1		±1		±1	ns
Input Clock Period Jitter (High Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_PER_JITT_DLL_HF			±1		±1		±1	ns
CLKIN (using CLKFX outputs)(2)	CLKIN_PER_JITT_FX_HF			±1		±1		±1	ns
Feedback Clock Path Delay Variation									
CLKFB off-chip feedback	CLKFB_DELAY_VAR_EXT			±1		±1		±1	ns

Notes:
1. "DLL outputs" is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. If both DLL and CLKFX outputs are used, follow the more restrictive specification.
3. If DCM phase shift feature is used and CLKIN frequency > 200 Mhz, CLKIN duty cycle must be within ±5% (45/55 to 55/45).

Date	Version	Revision
11/17/04	4.1	• Figure 8, Figure 9: Corrected T_{CCO} / DOUT to refer to the falling edge of CCLK. • Table 23: Added Footnote (4) to T_{PHASE} indicating an 8B/10B-type bitstream. Corrected T_{LOCK} from Typ to Max specification. Additional description of "2X oversampling" added to half-rate operation condition for F_{GCLK}, and added Footnote (2) requiring use of oversampling techniques in XAPP572 for serial bit rates under 1 Gb/s. • Table 25: Converted bit rate conditions for jitter parameters into four ranges. Added Footnote (2) requiring use of oversampling techniques in XAPP572 for serial bit rates under 1 Gb/s. • Table 27: Additional description of "2X oversampling" added to half-speed clock description for F_{GGTX}. Converted bit rate conditions for jitter parameters into four ranges. Added Footnotes (3) and (4) requiring use of oversampling techniques in XAPP572 for serial bit rates under 1 Gb/s. • Table 40: Changed capacitance C_{REF} for all PCI/PCI-X standards from 0 pF to 10 pF. • Table 49: Added Min/Max specifications for T_{ICCK}. • Section Power-On Power Supply Requirements, page 5: Added word "monotonically" to description of V_{CCINT} ramp-on requirements. Removed requirement that V_{CCAUX} must be powered on before or with V_{CCO}.
03/01/05	4.2	• Updated values in Virtex-II Pro Performance Characteristics and Virtex-II Pro Switching Characteristics tables, based on values extracted from **speedsfile version 1.90**. • Table 1 and Table 2: Corrected VCCAUXTX and VCCAUXRX to AVCCAUXTX and AVCCAUXRX respectively. • Table 3: Further clarified P_{RXTX} (MGT power dissipation) by explaining measurement method in Footnote (3). • Table 5: Added power-on current specifications for XC2VPX70 device. • Table 22: Changed F_{GTOL} from ±100 ppm to ±350 ppm. • Table 22 and Table 23: Changed T_{GJTT} bit rate qualifiers from fixed bit rates to bit rate ranges. • Table 36, Table 38, Table 39, and Table 40: Restructured these I/O-related tables to include descriptions, as well as the actual IOSTANDARD attributes (used in the Xilinx ICE™ software) for all I/O standards. • Table 36: Rearranged I/O standards in a more logical order. • Table 37: Added parameter T_{RPW} (Minimum Pulse Width, SR Input). • Table 38: Changed "Csl" to "C_{REF}" to agree with Figure 6 and Table 40. Rearranged I/O standards in a more logical order. • Table 39: Added footnote defining equivalents for DCI standards. • Table 40: Added Footnotes (2) and (3) to PCI/PCI-X capacitive load (C_{REF}) values. • Table 47: Added parameter T_{BCCS}, CLKA to CLKB Setup Time. • Table 50: Added Footnote (1) indicating that F_{CC_SERIAL} should not exceed $F_{CC\_STARTUP}$ if CCLK frequency is not adjustable. • Table 52: T_{TCKTDO} corrected from a "Min" to a "Max" specification.
06/20/05	4.3	• Table 12: Added specifications for Differential Input Impedance.

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
1	IO_L07P_1	F14			
1	IO_L06N_1	C15			
1	IO_L06P_1	D15			
1	IO_L05_1/No_Pair	E15			
1	IO_L03N_1/VREF_1	C16			
1	IO_L03P_1	D16			
1	IO_L02N_1	E16			
1	IO_L02P_1	E17			
1	IO_L01N_1/VRP_1	D17			
1	IO_L01P_1/VRN_1	D18			
2	IO_L01N_2/VRP_2	C21			
2	IO_L01P_2/VRN_2	C22			
2	IO_L02N_2	D21			
2	IO_L02P_2	D22			
2	IO_L03N_2	E19			
2	IO_L03P_2	E20			
2	IO_L04N_2/VREF_2	E21			
2	IO_L04P_2	E22			
2	IO_L06N_2	F19			
2	IO_L06P_2	F20			
2	IO_L43N_2	F21	NC		
2	IO_L43P_2	F22	NC		
2	IO_L46N_2/VREF_2	F18	NC		
2	IO_L46P_2	G18	NC		
2	IO_L48N_2	G19	NC		
2	IO_L48P_2	G20	NC		
2	IO_L49N_2	G21	NC		
2	IO_L49P_2	G22	NC		
2	IO_L50N_2	H19	NC		
2	IO_L50P_2	H20	NC		
2	IO_L52N_2/VREF_2	H21	NC		
2	IO_L52P_2	H22	NC		
2	IO_L54N_2	H18	NC		
2	IO_L54P_2	J17	NC		
2	IO_L55N_2	J19	NC		
2	IO_L55P_2	J20	NC		

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
3	IO_L49N_3	T22	NC		
3	IO_L49P_3	T21	NC		
3	IO_L48N_3	T20	NC		
3	IO_L48P_3	T19	NC		
3	IO_L47N_3	T18	NC		
3	IO_L47P_3	U18	NC		
3	IO_L45N_3/VREF_3	U22	NC		
3	IO_L45P_3	U21	NC		
3	IO_L43N_3	U20	NC		
3	IO_L43P_3	U19	NC		
3	IO_L06N_3	V22			
3	IO_L06P_3	V21			
3	IO_L05N_3	V20			
3	IO_L05P_3	V19			
3	IO_L03N_3/VREF_3	W22			
3	IO_L03P_3	W21			
3	IO_L02N_3	Y22			
3	IO_L02P_3	Y21			
3	IO_L01N_3/VRP_3	AA22			
3	IO_L01P_3/VRN_3	AB21			
4	IO_L01N_4/BUSY/DOUT(1)	W18			
4	IO_L01P_4/INIT_B	W17			
4	IO_L02N_4/D0/DIN(1)	V17			
4	IO_L02P_4/D1	V16			
4	IO_L03N_4/D2	W16			
4	IO_L03P_4/D3	Y16			
4	IO_L05_4/No_Pair	V15			
4	IO_L06N_4/VRP_4	W15			
4	IO_L06P_4/VRN_4	Y15			
4	IO_L07N_4	U14			
4	IO_L07P_4/VREF_4	V14			
4	IO_L09N_4	W14			
4	IO_L09P_4/VREF_4	W13			
4	IO_L67N_4	U13			
4	IO_L67P_4	V13			
4	IO_L69N_4	Y13			

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	VCCAUX	L1			
N/A	VCCAUX	B21			
N/A	VCCAUX	B2			
N/A	VCCAUX	AB11			
N/A	VCCAUX	AA21			
N/A	VCCAUX	AA2			
N/A	VCCAUX	A12			
N/A	GND	Y3			
N/A	GND	Y20			
N/A	GND	W4			
N/A	GND	W19			
N/A	GND	V5			
N/A	GND	V18			
N/A	GND	P9			
N/A	GND	P14			
N/A	GND	P13			
N/A	GND	P12			
N/A	GND	P11			
N/A	GND	P10			
N/A	GND	N9			
N/A	GND	N14			
N/A	GND	N13			
N/A	GND	N12			
N/A	GND	N11			
N/A	GND	N10			
N/A	GND	M9			
N/A	GND	M14			
N/A	GND	M13			
N/A	GND	M12			
N/A	GND	M11			
N/A	GND	M10			
N/A	GND	M1			
N/A	GND	L9			
N/A	GND	L22			
N/A	GND	L14			
N/A	GND	L13			
N/A	GND	L12			

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
3	IO_L36N_3	AE4		
3	IO_L36P_3	AF4		
3	IO_L35N_3	AC10		
3	IO_L35P_3	AD10		
3	IO_L34N_3	AE1		
3	IO_L34P_3	AE2		
3	IO_L33N_3/VREF_3	AF6		
3	IO_L33P_3	AF7		
3	IO_L32N_3	AC8		
3	IO_L32P_3	AC9		
3	IO_L31N_3	AF2		
3	IO_L31P_3	AF3		
3	IO_L30N_3	AG5		
3	IO_L30P_3	AG6		
3	IO_L29N_3	AD9		
3	IO_L29P_3	AE9		
3	IO_L28N_3	AG4		
3	IO_L28P_3	AH3		
3	IO_L27N_3/VREF_3	AG2		
3	IO_L27P_3	AG3		
3	IO_L26N_3	AD7		
3	IO_L26P_3	AE7		
3	IO_L25N_3	AH6		
3	IO_L25P_3	AH7		
3	IO_L24N_3	AH5		
3	IO_L24P_3	AJ5		
3	IO_L23N_3	AE8		
3	IO_L23P_3	AF8		
3	IO_L22N_3	AH1		
3	IO_L22P_3	AH2		
3	IO_L21N_3/VREF_3	AJ6		
3	IO_L21P_3	AK6		
3	IO_L20N_3	AG7		
3	IO_L20P_3	AG8		
3	IO_L19N_3	AJ3		
3	IO_L19P_3	AJ4		
3	IO_L18N_3	AJ1		
3	IO_L18P_3	AJ2		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
2	IO_L11N_2	L9		
2	IO_L11P_2	M10		
2	IO_L12N_2	H4		
2	IO_L12P_2	J5		
2	IO_L13N_2	J1		
2	IO_L13P_2	J2		
2	IO_L14N_2	M8		
2	IO_L14P_2	N9		
2	IO_L15N_2	K6		
2	IO_L15P_2	K7		
2	IO_L16N_2/VREF_2	K4		
2	IO_L16P_2	K5		
2	IO_L17N_2	P10		
2	IO_L17P_2	N10		
2	IO_L18N_2	K3		
2	IO_L18P_2	J3		
2	IO_L19N_2	K1		
2	IO_L19P_2	K2		
2	IO_L20N_2	M11		
2	IO_L20P_2	N11		
2	IO_L21N_2	L7		
2	IO_L21P_2	L8		
2	IO_L22N_2/VREF_2	L5		
2	IO_L22P_2	L6		
2	IO_L23N_2	P8		
2	IO_L23P_2	P9		
2	IO_L24N_2	L3		
2	IO_L24P_2	L4		
2	IO_L25N_2	L1		
2	IO_L25P_2	L2		
2	IO_L26N_2	P11		
2	IO_L26P_2	P12		
2	IO_L27N_2	M6		
2	IO_L27P_2	M7		
2	IO_L28N_2/VREF_2	M2		
2	IO_L28P_2	M3		
2	IO_L29N_2	R9		
2	IO_L29P_2	R10		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
5	IO_L29N_5	AK26	NC	
5	IO_L29P_5	AL26	NC	
5	IO_L28N_5	AL27	NC	
5	IO_L28P_5	AM27	NC	
5	IO_L27N_5/VREF_5	AR28		
5	IO_L27P_5	AT28		
5	IO_L26N_5	AH26		
5	IO_L26P_5	AH27		
5	IO_L25N_5	AL28		
5	IO_L25P_5	AM28		
5	IO_L21N_5	AT29		
5	IO_L21P_5	AU29		
5	IO_L20N_5	AJ27		
5	IO_L20P_5	AJ28		
5	IO_L19N_5	AP29		
5	IO_L19P_5	AR29		
5	IO_L09N_5/VREF_5	AM29		
5	IO_L09P_5	AN29		
5	IO_L08N_5	AK29		
5	IO_L08P_5	AL29		
5	IO_L07N_5/VREF_5	AT30		
5	IO_L07P_5	AU30		
5	IO_L06N_5/VRP_5	AP30		
5	IO_L06P_5/VRN_5	AR30		
5	IO_L05_5/No_Pair	AK28		
5	IO_L03N_5/D4	AM30		
5	IO_L03P_5/D5	AN30		
5	IO_L02N_5/D6	AL30		
5	IO_L02P_5/D7	AK30		
5	IO_L01N_5/RDWR_B	AR31		
5	IO_L01P_5/CS_B	AT31		
6	IO_L01P_6/VRN_6	AU33		
6	IO_L01N_6/VRP_6	AT33		
6	IO_L02P_6	AT32		
6	IO_L02N_6	AR32		
6	IO_L03P_6	AN31		
6	IO_L03N_6/VREF_6	AM31		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
4	IO_L60P_4		AR19		
4	IO_L64N_4		AV19		
4	IO_L64P_4		AU19		
4	IO_L65N_4		AW19		
4	IO_L65P_4		AY19		
4	IO_L66N_4		AL21		
4	IO_L66P_4/VREF_4		AL20		
4	IO_L67N_4		AN20		
4	IO_L67P_4		AM20		
4	IO_L68N_4		AP20		
4	IO_L68P_4		AR20		
4	IO_L69N_4		AV20		
4	IO_L69P_4/VREF_4		AU20		
4	IO_L73N_4		AY20		
4	IO_L73P_4		AW20		
4	IO_L74N_4/GCLK3S		AN21		
4	IO_L74P_4/GCLK2P		AP21		
4	IO_L75N_4/GCLK1S		AU21		
4	IO_L75P_4/GCLK0P		AT21		
5	IO_L75N_5/GCLK7S	BREFCLKN	AT22		
5	IO_L75P_5/GCLK6P	BREFCLKP	AU22		
5	IO_L74N_5/GCLK5S		AP22		
5	IO_L74P_5/GCLK4P		AN22		
5	IO_L73N_5		AW23		
5	IO_L73P_5		AY23		
5	IO_L69N_5/VREF_5		AU23		
5	IO_L69P_5		AV23		
5	IO_L68N_5		AR23		
5	IO_L68P_5		AP23		
5	IO_L67N_5		AM23		
5	IO_L67P_5		AN23		
5	IO_L66N_5/VREF_5		AL23		
5	IO_L66P_5		AL22		
5	IO_L65N_5		AY24		
5	IO_L65P_5		AW24		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
5	IO_L37N_5		AU28		
5	IO_L37P_5		AV28		
5	IO_L87N_5/VREF_5		AP28	NC	
5	IO_L87P_5		AR28	NC	
5	IO_L86N_5		AN28	NC	
5	IO_L86P_5		AM28	NC	
5	IO_L85N_5		AV29	NC	
5	IO_L85P_5		AW29	NC	
5	IO_L84N_5		AT29	NC	
5	IO_L84P_5		AU29	NC	
5	IO_L83_5/No_Pair		AR29	NC	
5	IO_L78N_5		AM29	NC	
5	IO_L78P_5		AN29	NC	
5	IO_L36N_5/VREF_5		AL29		
5	IO_L36P_5		AL28		
5	IO_L35N_5		AY30		
5	IO_L35P_5		AW30		
5	IO_L34N_5		AU30		
5	IO_L34P_5		AV30		
5	IO_L30N_5		AR30		
5	IO_L30P_5		AT30		
5	IO_L29N_5		AN30		
5	IO_L29P_5		AP30		
5	IO_L28N_5		AL30		
5	IO_L28P_5		AM30		
5	IO_L27N_5/VREF_5		AV31		
5	IO_L27P_5		AW31		
5	IO_L26N_5		AU31		
5	IO_L26P_5		AT31		
5	IO_L25N_5		AP31		
5	IO_L25P_5		AR31		
5	IO_L21N_5		AM31		
5	IO_L21P_5		AN31		
5	IO_L20N_5		AY32		
5	IO_L20P_5		AY33		
5	IO_L19N_5		AU32		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
6	IO_L52N_6		AE42		
6	IO_L53P_6		AE32		
6	IO_L53N_6		AE33		
6	IO_L54P_6		AD35		
6	IO_L54N_6		AD36		
6	IO_L55P_6		AD37		
6	IO_L55N_6		AD38		
6	IO_L56P_6		AD31		
6	IO_L56N_6		AD32		
6	IO_L57P_6		AD39		
6	IO_L57N_6/VREF_6		AD40		
6	IO_L58P_6		AD41		
6	IO_L58N_6		AD42		
6	IO_L59P_6		AD33		
6	IO_L59N_6		AD34		
6	IO_L60P_6		AC33		
6	IO_L60N_6		AC34		
6	IO_L85P_6		AC36		
6	IO_L85N_6		AC37		
6	IO_L86P_6		AC31		
6	IO_L86N_6		AC32		
6	IO_L87P_6		AC39		
6	IO_L87N_6/VREF_6		AC40		
6	IO_L88P_6		AB33		
6	IO_L88N_6		AB34		
6	IO_L89P_6		AB36		
6	IO_L89N_6		AB37		
6	IO_L90P_6		AB39		
6	IO_L90N_6		AB40		
7	IO_L90P_7		AA39		
7	IO_L90N_7		AA40		
7	IO_L89P_7		AB31		
7	IO_L89N_7		AA31		
7	IO_L88P_7		AA36		
7	IO_L88N_7/VREF_7		AA37		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
7	VCCO_7		T29		
7	VCCO_7		T28		
7	VCCO_7		R29		
7	VCCO_7		P39		
7	VCCO_7		M37		
7	VCCO_7		J40		
7	VCCO_7		F38		
N/A	CCLK		AY7		
N/A	PROG_B		G35		
N/A	DONE		AW8		
N/A	M0		AV35		
N/A	M1		AY36		
N/A	M2		AW35		
N/A	TCK		G8		
N/A	TDI		C36		
N/A	TDO		C7		
N/A	TMS		F8		
N/A	PWRDWN_B		AV8		
N/A	HSWAP_EN		F35		
N/A	RSVD		D8		
N/A	VBATT		E8		
N/A	DXP		E35		
N/A	DXN		D35		
N/A	AVCCAUXTX2		B40		
N/A	VTTXPAD2		B41		
N/A	TXNPAD2		A41		
N/A	TXPPAD2		A40		
N/A	GNDA2		C39		
N/A	RXPPAD2		A39		
N/A	RXNPAD2		A38		
N/A	VTRXPAD2		B39		
N/A	AVCCAUXRX2		B38		
N/A	AVCCAUXTX3		B36		
N/A	VTTXPAD3		B37		
N/A	TXNPAD3		A37		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
1	IO_L87N_1/VREF_1	C15	
1	IO_L87P_1	C16	
1	IO_L86N_1	K15	
1	IO_L86P_1	J15	
1	IO_L85N_1	F15	
1	IO_L85P_1	E15	
1	IO_L84N_1	G15	
1	IO_L84P_1	G16	
1	IO_L83_1/No_Pair	M15	
1	IO_L80_1/No_Pair	L15	
1	IO_L79N_1	B14	
1	IO_L79P_1	A14	
1	IO_L78N_1	C14	
1	IO_L78P_1	D15	
1	IO_L77N_1	K14	
1	IO_L77P_1	J14	
1	IO_L76N_1	F14	
1	IO_L76P_1	E14	
1	IO_L36N_1/VREF_1	G14	
1	IO_L36P_1	H15	
1	IO_L35N_1	M14	
1	IO_L35P_1	L14	
1	IO_L34N_1	C13	
1	IO_L34P_1	B13	
1	IO_L30N_1	G13	
1	IO_L30P_1	F13	
1	IO_L29N_1	L13	
1	IO_L29P_1	K13	
1	IO_L28N_1	C12	
1	IO_L28P_1	B12	
1	IO_L27N_1/VREF_1	D12	
1	IO_L27P_1	D13	
1	IO_L26N_1	J12	
1	IO_L26P_1	H12	
1	IO_L25N_1	F12	
1	IO_L25P_1	E12	
1	IO_L21N_1	G12	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
5	IO_L34P_5	AU30	
5	IO_L30N_5	AM30	
5	IO_L30P_5	AN30	
5	IO_L29N_5	AY31	
5	IO_L29P_5	BA31	
5	IO_L28N_5	AW31	
5	IO_L28P_5	AW30	
5	IO_L27N_5/VREF_5	AP31	
5	IO_L27P_5	AR31	
5	IO_L26N_5	AU31	
5	IO_L26P_5	AV31	
5	IO_L25N_5	AT31	
5	IO_L25P_5	AR30	
5	IO_L21N_5	AM31	
5	IO_L21P_5	AN31	
5	IO_L20N_5	BA32	
5	IO_L20P_5	BB32	
5	IO_L19N_5	AV32	
5	IO_L19P_5	AW32	
5	IO_L09N_5/VREF_5	AP32	
5	IO_L09P_5	AR32	
5	IO_L08N_5	AT32	
5	IO_L08P_5	AU32	
5	IO_L07N_5/VREF_5	BA33	
5	IO_L07P_5	BB33	
5	IO_L06N_5/VRP_5	AY33	
5	IO_L06P_5/VRN_5	AY32	
5	IO_L05_5/No_Pair	AT33	
5	IO_L03N_5/D4	AM32	
5	IO_L03P_5/D5	AN32	
5	IO_L02N_5/D6	AU33	
5	IO_L02P_5/D7	AV33	
5	IO_L01N_5/RDWR_B	AL31	
5	IO_L01P_5/CS_B	AL32	
6	IO_L01P_6/VRN_6	BB39	
6	IO_L01N_6/VRP_6	BA39	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	GND	BB34	
N/A	GND	AV34	
N/A	GND	AP34	
N/A	GND	AK34	
N/A	GND	AF34	
N/A	GND	AC34	
N/A	GND	Y34	
N/A	GND	U34	
N/A	GND	N34	
N/A	GND	J34	
N/A	GND	E34	
N/A	GND	A34	
N/A	GND	AD31	
N/A	GND	W31	
N/A	GND	BB30	
N/A	GND	AV30	
N/A	GND	AP30	
N/A	GND	J30	
N/A	GND	E30	
N/A	GND	A30	
N/A	GND	BB26	
N/A	GND	AV26	
N/A	GND	AP26	
N/A	GND	AE26	
N/A	GND	AD26	
N/A	GND	AC26	
N/A	GND	AB26	
N/A	GND	AA26	
N/A	GND	Y26	
N/A	GND	W26	
N/A	GND	V26	
N/A	GND	J26	
N/A	GND	E26	
N/A	GND	A26	
N/A	GND	AF25	
N/A	GND	AE25	
N/A	GND	AD25	